

CLAIM AMENDMENTS

Please amend the claims as follows:

1. (Currently amended) A device for thermal management of an LED, said device comprising:
  - a heatsink;
  - a substrate overlying said heatsink;
  - a trace layer overlying and adjacent to said substrate;
  - a pad overlying and adjacent to said trace layer, said pad being operable to mount said LED; and
  - a via extending through said substrate, wherein said via is in thermal communication with said trace layer and said heatsink to transfer to said heatsink at least a portion of any heat applied to said trace layer by said LED.
2. (Currently amended) The device of claim 1, further comprising:
  - a bonding layer between said substrate and said ~~via~~ heatsink.
3. (Previously presented) The device of claim 2, wherein said bonding layer is a thermally conductive adhesive.
4. (Previously presented) The device of claim 2, wherein said bonding layer is a thermally conductive tape.
5. (Previously presented) The device of claim 1, wherein said substrate is a multi-layered substrate.
6. (Previously presented) The device of claim 1, wherein said substrate is a printed circuit board.

7. (Previously presented) The device of claim 1, wherein said substrate is a flexible substrate.

8. (Previously presented) The device of claim 1, wherein said via includes: a sidewall defining a channel through said substrate, said channel interfacing with said trace layer to thereby establish the thermal communication between said via and said trace layer.

9. (Previously presented) The device of claim 8, further comprising:  
a thermal conductive material filling at least a portion of said channel.

10. (Previously presented) The device of claim 1, wherein said via includes:  
a sidewall defining a channel through said substrate, said channel interfacing with said heat sink to thereby establish the thermal communication between said via and said heat sink.

11. (Previously presented) The device of claim 10, further comprising:  
a thermal conductive material filling at least a portion of said channel.

12. (Previously presented) A device for thermal management of an LED, said device comprising:

a heatsink;  
a trace layer; and  
a flexible substrate in thermal communication with said trace layer and said heatsink to transfer to said heatsink any heat applied to said trace layer by said LED.

13. (Previously presented) The device of claim 12, further comprising:  
a via extending through said substrate, wherein said via is in thermal communication with said trace layer and said heatsink to enhance the transfer to said heatsink of any heat applied to said trace layer by said LED.

14. (Previously presented) The device of claim 13, wherein said via includes:  
a sidewall defining a channel through said substrate, said channel interfacing with  
said trace layer to thereby establish the thermal communication between said via and said trace  
layer.
15. (Previously presented) The device of claim 14, further comprising:  
a thermal conductive material filling at least a portion of said channel.
16. (Previously presented) The device of claim 13, wherein said via includes:  
a sidewall defining a channel through said substrate, said channel interfacing  
with said heat sink to thereby establish the thermal communication between said via and said  
heat sink.
17. (Previously presented) The device of claim 16, further comprising:  
a thermal conductive material filling at least a portion of said channel.
18. (Currently amended) A device for thermal management of an LED, said device  
comprising:  
a heatsink;  
a substrate overlying said heatsink;  
a trace layer overlying and adjacent to said substrate;  
a pad overlying and adjacent to said trace layer, said pad being operable to mount  
said LED; and  
a via including a sidewall defining a channel extending through said substrate,  
wherein said channel is beneath said trace layer and above said heatsink to transfer any heat  
applied to said trace layer by said LED to said heatsink.

19. (Previously presented) The device of claim 18, further comprising:  
a thermal conductive material filling at least a portion of said channel.
20. (Currently amended) The device of claim 18, further comprising:  
a bonding layer between said substrate and said ~~via~~ heatsink.
21. (New) The device of claim 1, wherein:  
said via includes a sidewall defining a channel through said substrate, said  
channel interfacing with said trace layer and said heat sink to thereby establish the thermal  
communication between said trace layer and said heat sink, a thermal conductive material filling  
at least a portion of said channel; and  
said thermal conductive material is different from the material of said sidewall.
22. (New) The device of claim 21, wherein:  
said thermal conductive material is solder and the material of said sidewall is  
copper.